

# PEMD3; PIMD3; PUMD3

NPN/PNP resistor-equipped transistors;  
R1 = 10 k $\Omega$ , R2 = 10 k $\Omega$

Rev. 11 — 25 September 2013

Product data sheet

## 1. Product profile

### 1.1 General description

NPN/PNP Resistor-Equipped Transistors (RET) in Surface-Mounted Device (SMD) plastic packages.

Table 1. Product overview

Type number	Package		PNP/PNP complement	NPN/PNP complement	Package configuration
	NXP	JEITA			
PEMD3	SOT666	-	PEMB11	PEMH11	ultra small and flat lead
PIMD3	SOT457	SC-74	-	-	small
PUMD3	SOT363	SC-88	PUMB11	PUMH11	very small

### 1.2 Features and benefits

- 100 mA output current capability
- Built-in bias resistors
- Simplifies circuit design
- Reduces component count
- Reduces pick and place costs
- AEC-Q101 qualified

### 1.3 Applications

- Low current peripheral driver
- Control of IC inputs
- Replaces general-purpose transistors in digital applications

### 1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor; for the PNP transistor (TR2) with negative polarity</b>						
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-	50	V
I <sub>O</sub>	output current		-	-	100	mA
R1	bias resistor 1 (input)		7	10	13	k $\Omega$
R2/R1	bias resistor ratio		0.8	1	1.2	



## 2. Pinning information

**Table 3. Pinning**

Pin	Description	Simplified outline	Graphic symbol
1	GND (emitter) TR1		
2	input (base) TR1		
3	output (collector) TR2		
4	GND (emitter) TR2		
5	input (base) TR2		
6	output (collector) TR1		

## 3. Ordering information

**Table 4. Ordering information**

Type number	Package		
	Name	Description	Version
PEMD3	-	plastic surface-mounted package; 6 leads	SOT666
PIMD3	SC-74	plastic surface-mounted package (TSOP6); 6 leads	SOT457
PUMD3	SC-88	plastic surface-mounted package; 6 leads	SOT363

## 4. Marking

**Table 5. Marking codes**

Type number	Marking code <sup>[1]</sup>
PEMD3	D3
PIMD3	M7
PUMD3	D*3

[1] \* = placeholder for manufacturing site code.

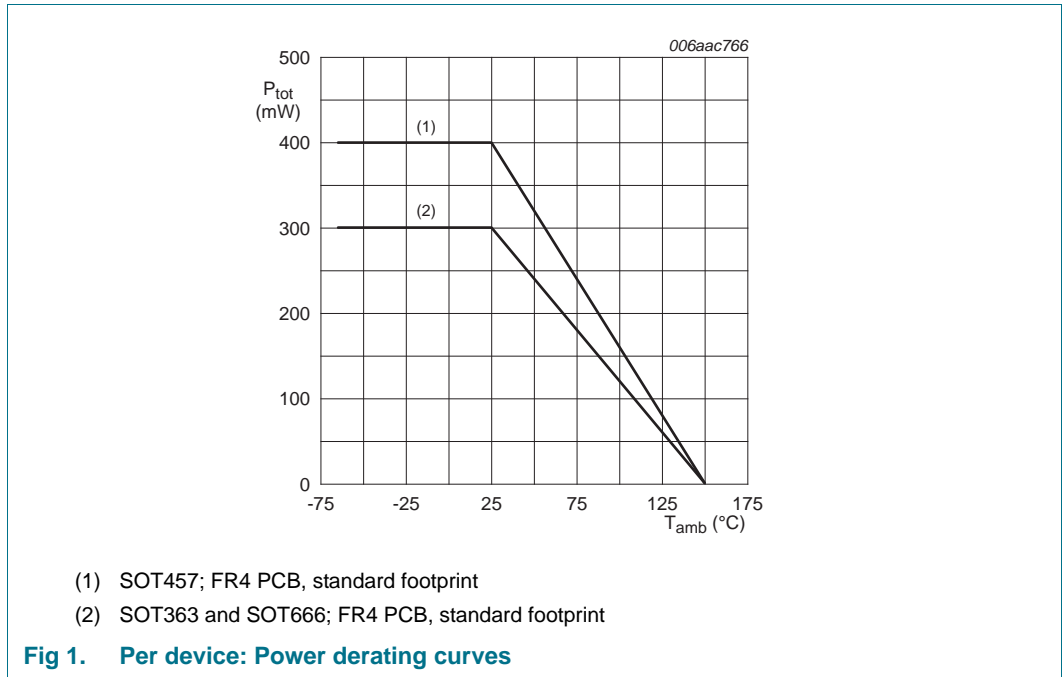
## 5. Limiting values

**Table 6. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
<b>Per transistor; for the PNP transistor (TR2) with negative polarity</b>					
$V_{CBO}$	collector-base voltage	open emitter	-	50	V
$V_{CEO}$	collector-emitter voltage	open base	-	50	V
$V_{EBO}$	emitter-base voltage	open collector	-	10	V
$V_I$	input voltage TR1				
		positive	-	+40	V
		negative	-	-10	V
	input voltage TR2				
		positive	-	+10	V
		negative	-	-40	V
$I_O$	output current		-	100	mA
$I_{CM}$	peak collector current		-	100	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[1]		
		PEMD3 (SOT666)	-	200	mW
		PIMD3 (SOT457)	-	250	mW
		PUMD3 (SOT363)	-	200	mW
<b>Per device</b>					
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[1]		
		PEMD3 (SOT666)	-	300	mW
		PIMD3 (SOT457)	-	400	mW
		PUMD3 (SOT363)	-	300	mW
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-65	+150	°C
$T_{stg}$	storage temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

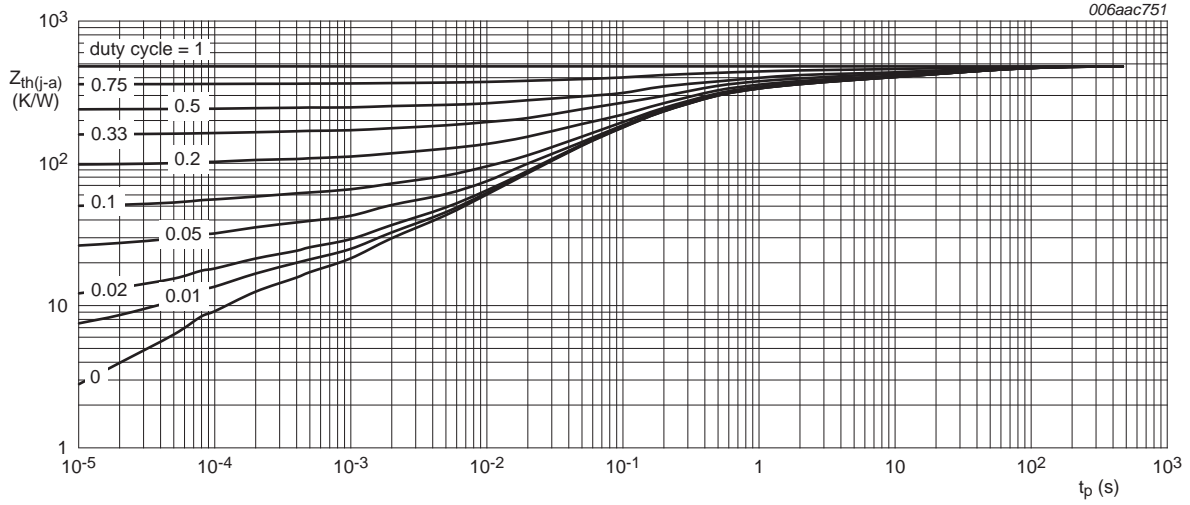


## 6. Thermal characteristics

**Table 7. Thermal characteristics**

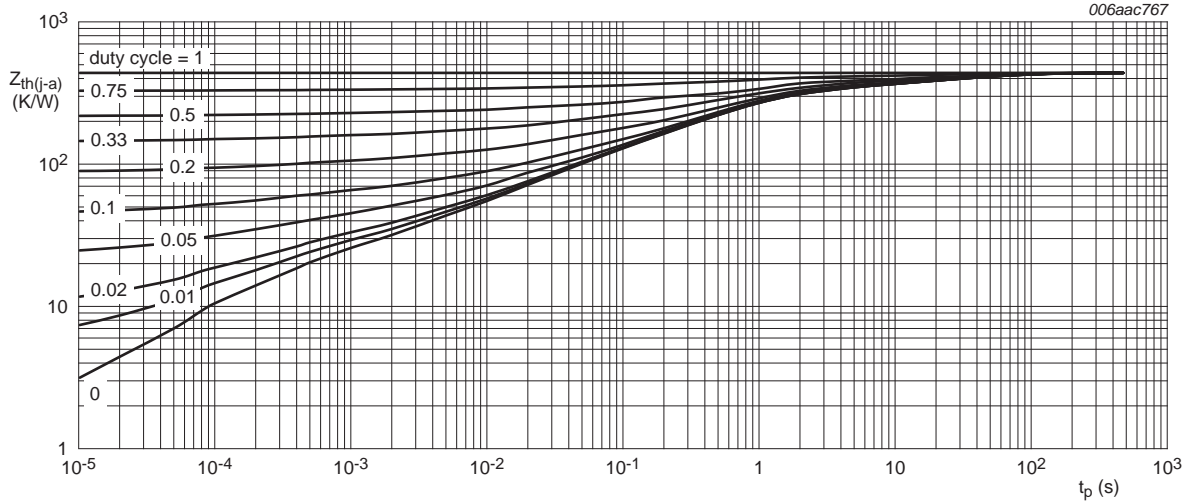
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor</b>						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]			
	PEMD3 (SOT666)		-	-	625	K/W
	PIMD3 (SOT457)		-	-	500	K/W
	PUMD3 (SOT363)		-	-	625	K/W
<b>Per device</b>						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]			
	PEMD3 (SOT666)		-	-	417	K/W
	PIMD3 (SOT457)		-	-	313	K/W
	PUMD3 (SOT363)		-	-	417	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.



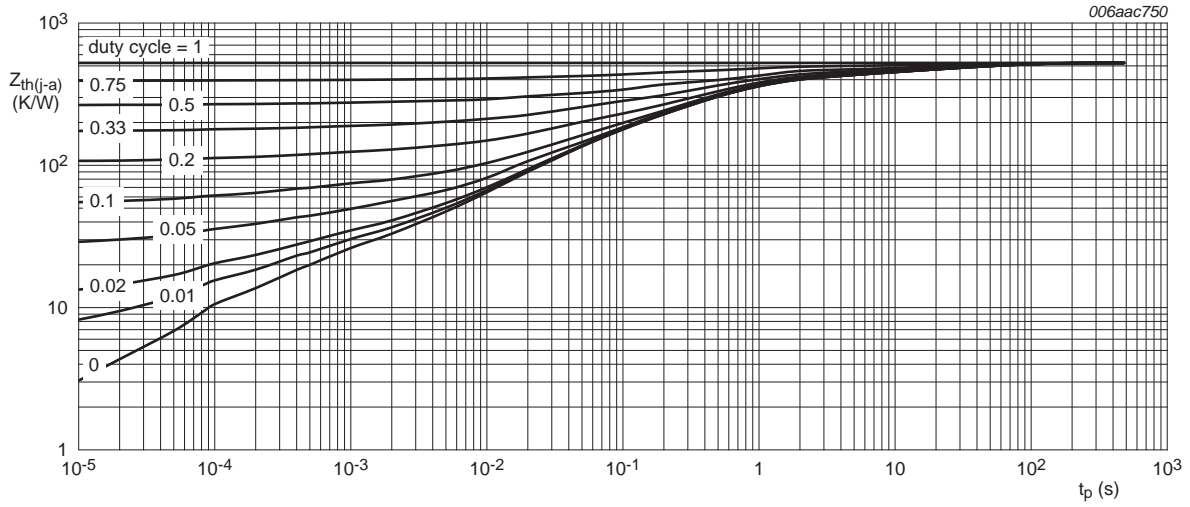
FR4 PCB, standard footprint

**Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration for PEMD3 (SOT666); typical values**



FR4 PCB, standard footprint

**Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration for PIMD3 (SOT457); typical values**



FR4 PCB, standard footprint

**Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration for PUMD3 (SOT363); typical values**

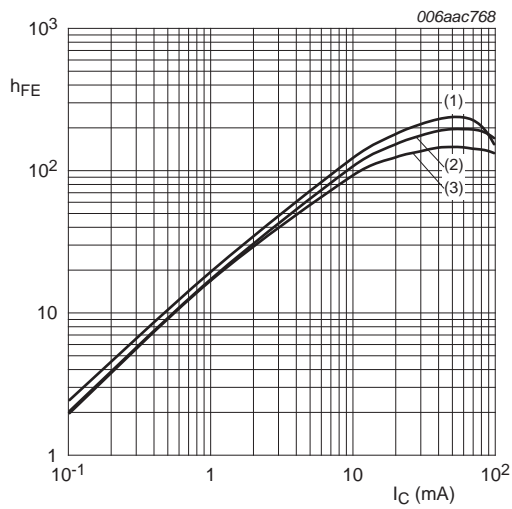
## 7. Characteristics

**Table 8. Characteristics**

$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

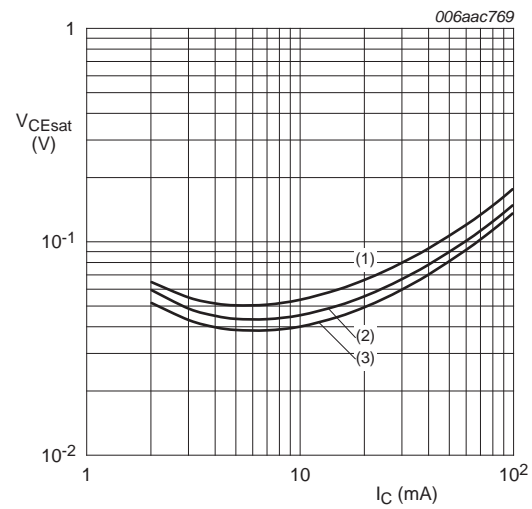
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor; for the PNP transistor (TR2) with negative polarity</b>						
$I_{CBO}$	collector-base cut-off current	$V_{CB} = 50\text{ V}; I_E = 0\text{ A}$	-	-	100	nA
$I_{CEO}$	collector-emitter cut-off current	$V_{CE} = 30\text{ V}; I_B = 0\text{ A}$	-	-	1	$\mu\text{A}$
		$V_{CE} = 30\text{ V}; I_B = 0\text{ A}; T_j = 150\text{ }^{\circ}\text{C}$	-	-	5	$\mu\text{A}$
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = 5\text{ V}; I_C = 0\text{ A}$	-	-	400	$\mu\text{A}$
$h_{FE}$	DC current gain	$V_{CE} = 5\text{ V}; I_C = 5\text{ mA}$	30	-	-	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = 10\text{ mA}; I_B = 0.5\text{ mA}$	-	-	150	mV
$V_{I(off)}$	off-state input voltage	$V_{CE} = 5\text{ V}; I_C = 100\text{ }\mu\text{A}$	-	1.1	0.8	V
$V_{I(on)}$	on-state input voltage	$V_{CE} = 0.3\text{ V}; I_C = 10\text{ mA}$	2.5	1.8	-	V
R1	bias resistor 1 (input)		7	10	13	k $\Omega$
R2/R1	bias resistor ratio		0.8	1	1.2	
$C_c$	collector capacitance	$V_{CB} = 10\text{ V}; I_E = I_e = 0\text{ A}; f = 1\text{ MHz}$				
		TR1 (NPN)	-	-	2.5	pF
		TR2 (PNP)	-	-	3	pF
$f_T$	transition frequency	$V_{CB} = 5\text{ V}; I_C = 10\text{ mA}; f = 100\text{ MHz}$	[1]			
		TR1 (NPN)	-	230	-	MHz
		TR2 (PNP)	-	180	-	MHz

[1] Characteristics of built-in transistor.



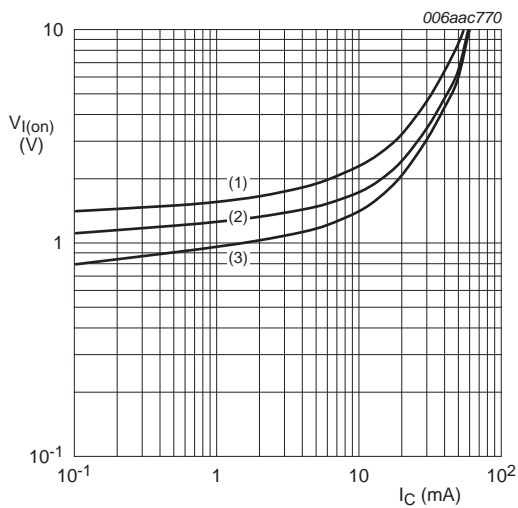
- $V_{CE} = 5\text{ V}$
- (1)  $T_{amb} = 100\text{ }^{\circ}\text{C}$
  - (2)  $T_{amb} = 25\text{ }^{\circ}\text{C}$
  - (3)  $T_{amb} = -40\text{ }^{\circ}\text{C}$

**Fig 5. TR1 (NPN): DC current gain as a function of collector current; typical values**



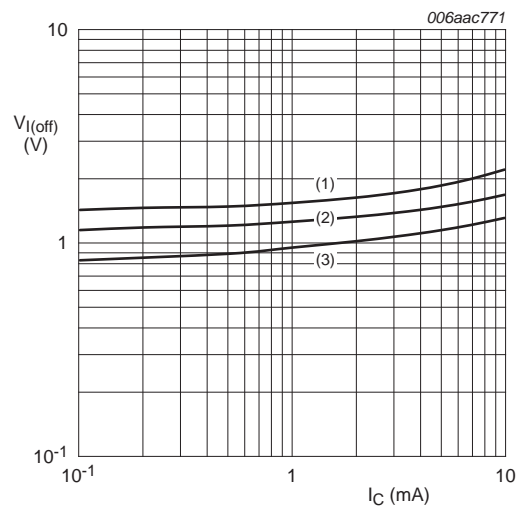
- $I_C/I_B = 20$
- (1)  $T_{amb} = 100\text{ }^{\circ}\text{C}$
  - (2)  $T_{amb} = 25\text{ }^{\circ}\text{C}$
  - (3)  $T_{amb} = -40\text{ }^{\circ}\text{C}$

**Fig 6. TR1 (NPN): Collector-emitter saturation voltage as a function of collector current; typical values**



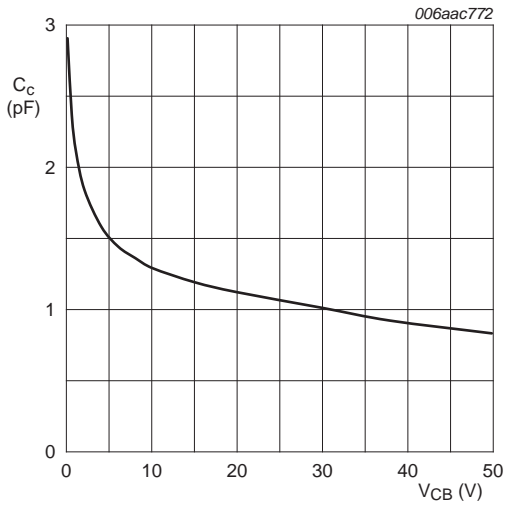
- $V_{CE} = 0.3\text{ V}$
- (1)  $T_{amb} = -40\text{ }^{\circ}\text{C}$
  - (2)  $T_{amb} = 25\text{ }^{\circ}\text{C}$
  - (3)  $T_{amb} = 100\text{ }^{\circ}\text{C}$

**Fig 7. TR1 (NPN): On-state input voltage as a function of collector current; typical values**



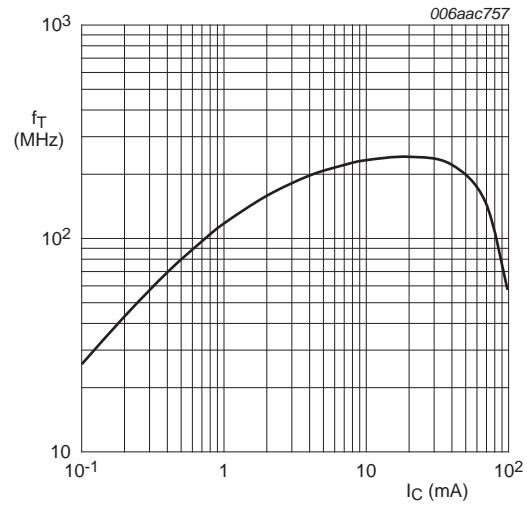
- $V_{CE} = 5\text{ V}$
- (1)  $T_{amb} = -40\text{ }^{\circ}\text{C}$
  - (2)  $T_{amb} = 25\text{ }^{\circ}\text{C}$
  - (3)  $T_{amb} = 100\text{ }^{\circ}\text{C}$

**Fig 8. TR1 (NPN): Off-state input voltage as a function of collector current; typical values**



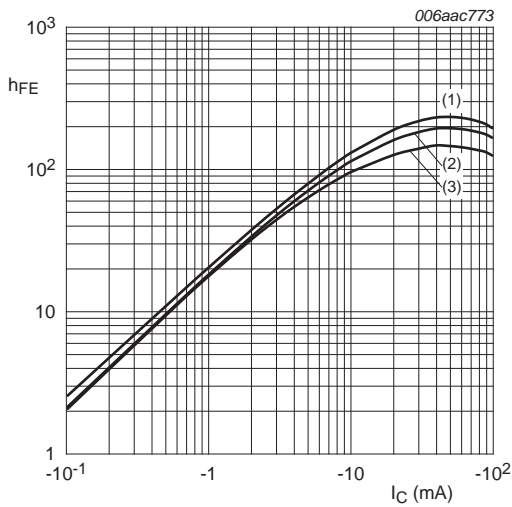
$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

**Fig 9. TR1 (NPN): Collector capacitance as a function of collector-base voltage; typical values**



$V_{\text{CE}} = 5 \text{ V}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

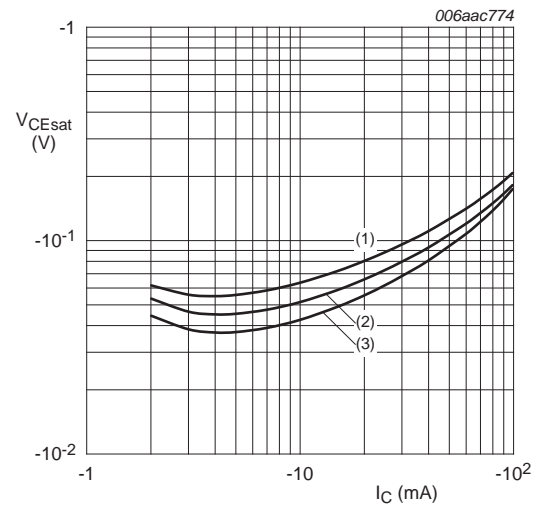
**Fig 10. TR1 (NPN): Transition frequency as a function of collector current; typical values of built-in transistor**



$V_{\text{CE}} = -5 \text{ V}$

- (1)  $T_{\text{amb}} = 100 \text{ }^\circ\text{C}$
- (2)  $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$
- (3)  $T_{\text{amb}} = -40 \text{ }^\circ\text{C}$

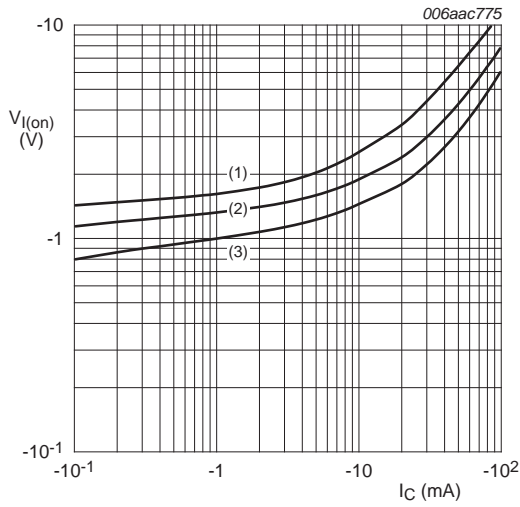
**Fig 11. TR2 (PNP): DC current gain as a function of collector current; typical values**



$I_{\text{C}}/I_{\text{B}} = 20$

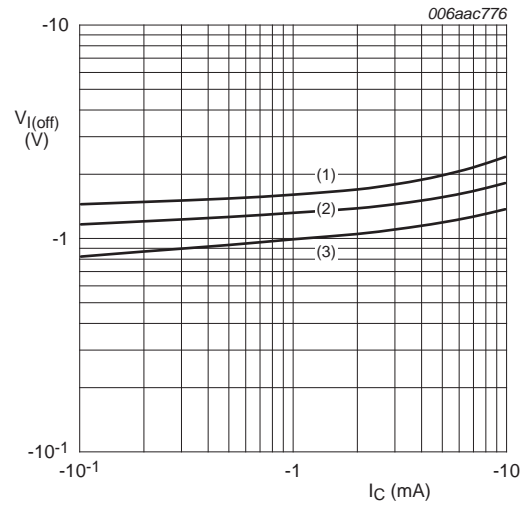
- (1)  $T_{\text{amb}} = 100 \text{ }^\circ\text{C}$
- (2)  $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$
- (3)  $T_{\text{amb}} = -40 \text{ }^\circ\text{C}$

**Fig 12. TR2 (PNP): Collector-emitter saturation voltage as a function of collector current; typical values**



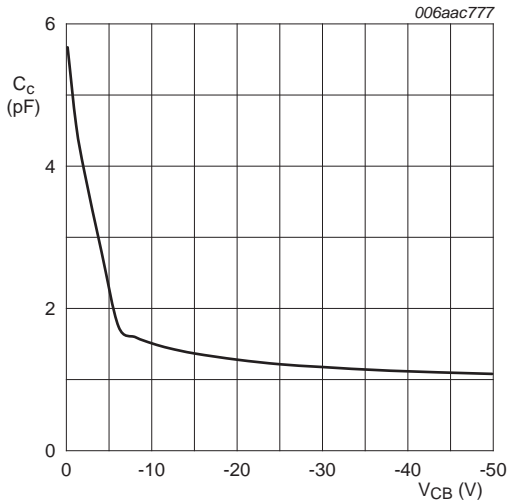
$V_{CE} = -0.3\text{ V}$   
 (1)  $T_{amb} = -40^\circ\text{C}$   
 (2)  $T_{amb} = 25^\circ\text{C}$   
 (3)  $T_{amb} = 100^\circ\text{C}$

**Fig 13. TR2 (PNP): On-state input voltage as a function of collector current; typical values**



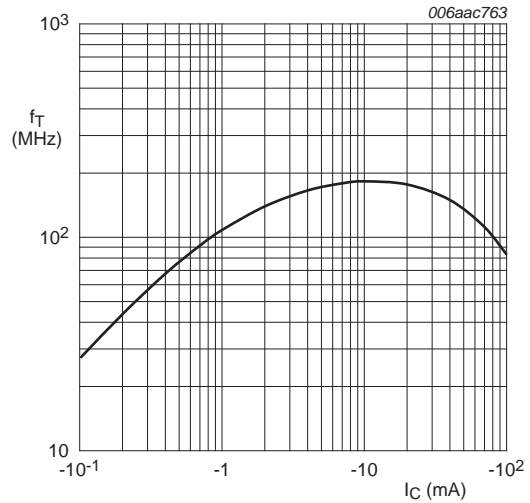
$V_{CE} = -5\text{ V}$   
 (1)  $T_{amb} = -40^\circ\text{C}$   
 (2)  $T_{amb} = 25^\circ\text{C}$   
 (3)  $T_{amb} = 100^\circ\text{C}$

**Fig 14. TR2 (PNP): Off-state input voltage as a function of collector current; typical values**



$f = 1\text{ MHz}; T_{amb} = 25^\circ\text{C}$

**Fig 15. TR2 (PNP): Collector capacitance as a function of collector-base voltage; typical values**



$V_{CE} = -5\text{ V}; T_{amb} = 25^\circ\text{C}$

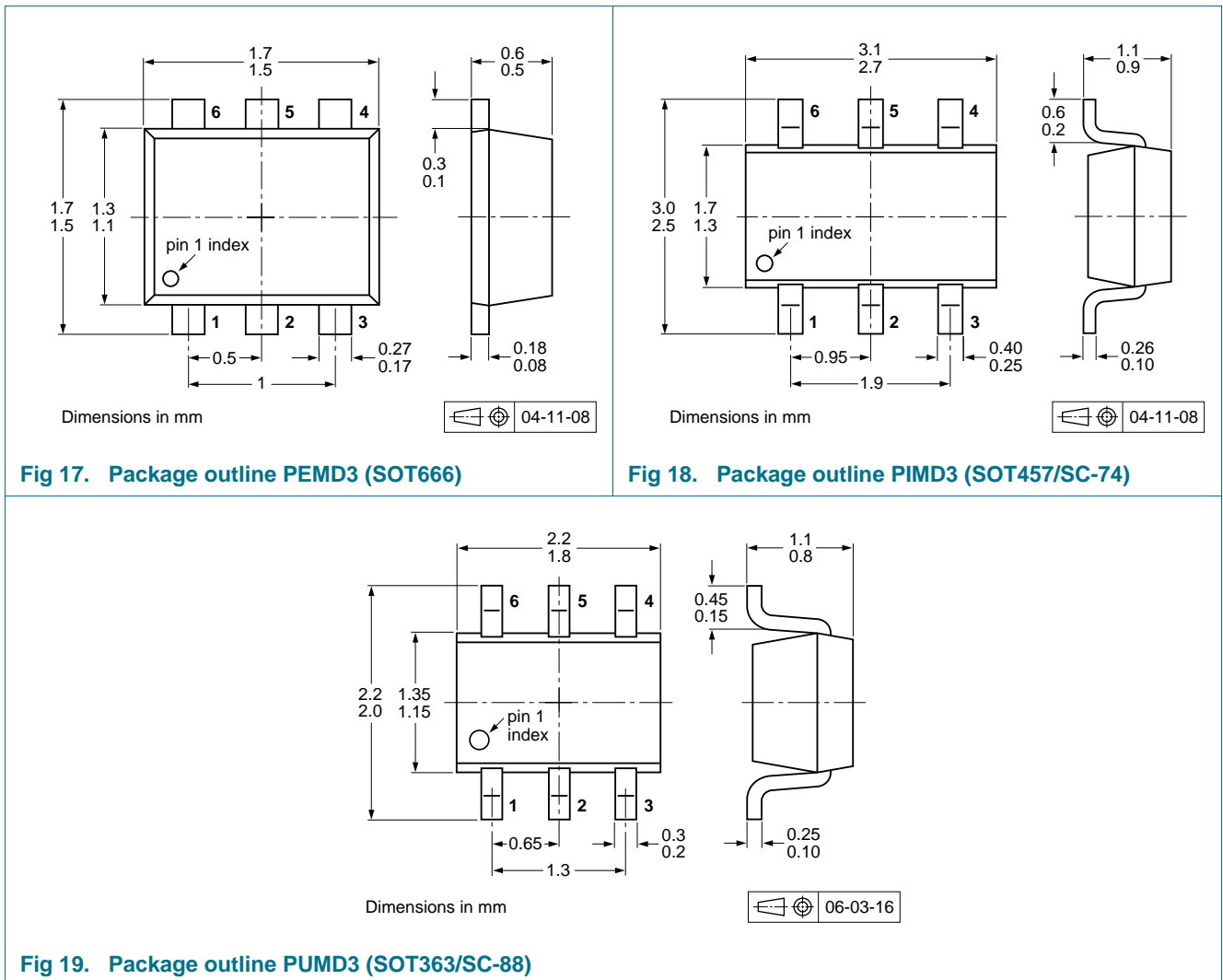
**Fig 16. TR2 (PNP): Transition frequency as a function of collector current; typical values of built-in transistor**

**8. Test information**

**8.1 Quality information**

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

**9. Package outline**



## 10. Soldering

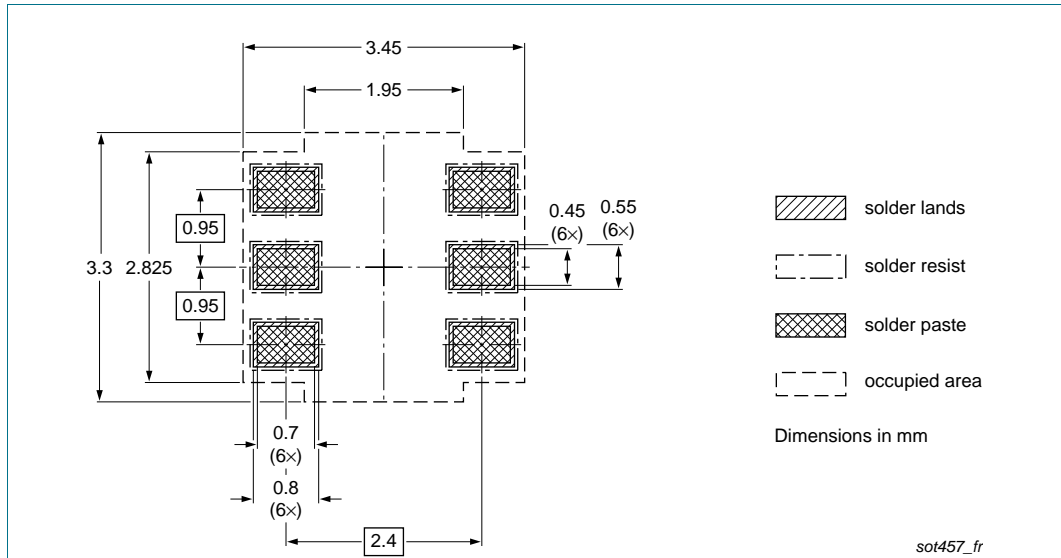


Fig 20. Reflow soldering footprint PIMD3 (SOT457/SC-74)

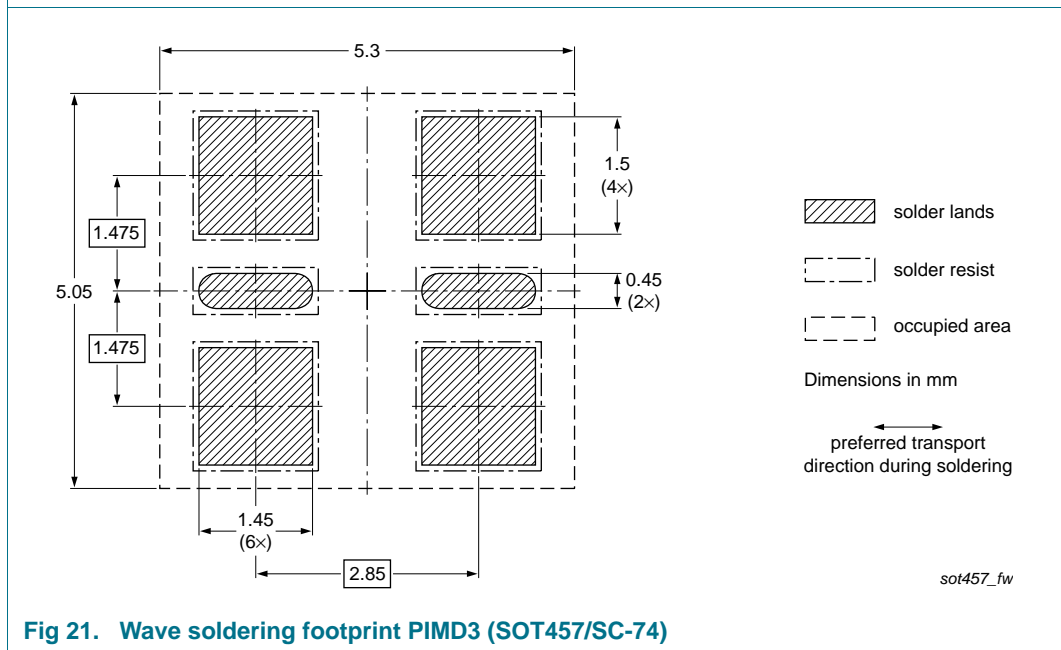


Fig 21. Wave soldering footprint PIMD3 (SOT457/SC-74)



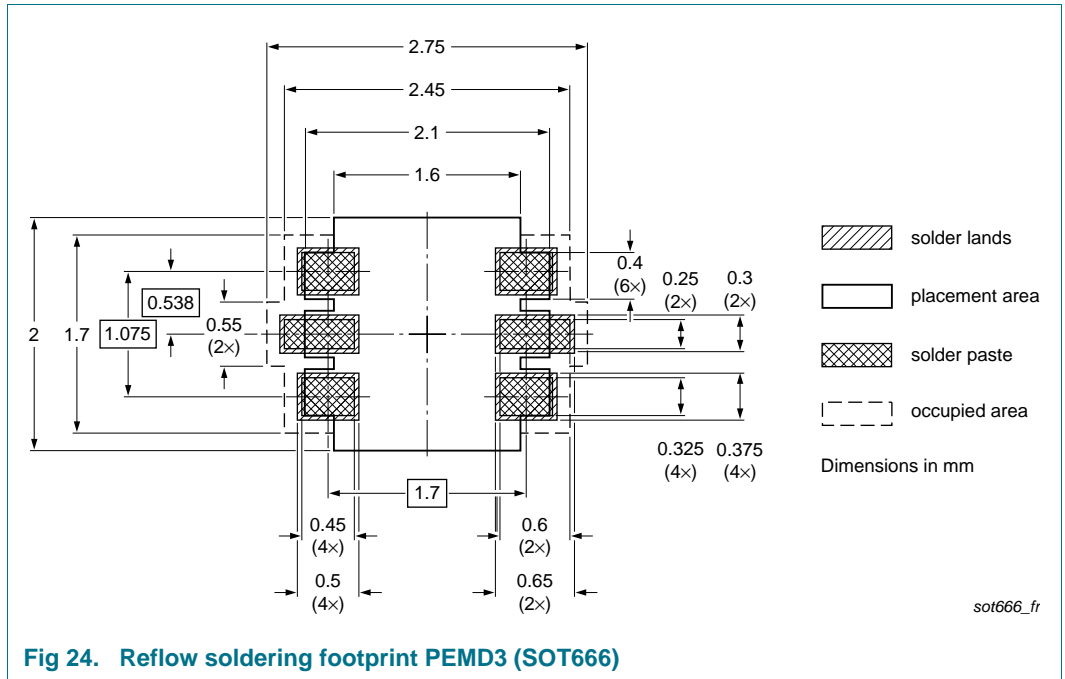


Fig 24. Reflow soldering footprint PEMD3 (SOT666)

## 11. Revision history

**Table 9.** Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PEMD3_PIMD3_PUMD3 v.11	20130925	Product data sheet	-	PEMD3_PIMD3_PUMD3 v.10
Modifications:		<ul style="list-style-type: none"> <li>• <a href="#">Section 1 “Product profile”</a>: updated</li> <li>• <a href="#">Section 4 “Marking”</a>: updated</li> <li>• <a href="#">Table 6 “Limiting values”</a>: <math>P_{tot}</math> updated according to the latest measurements</li> <li>• <a href="#">Table 7 “Thermal characteristics”</a>: updated according to the latest measurements</li> <li>• <a href="#">Table 8 “Characteristics”</a>: <math>I_{CEO}</math> updated according to the latest measurements, <math>f_T</math> added</li> <li>• <a href="#">Figure 1</a> to <a href="#">3</a>, <a href="#">9</a>, <a href="#">10</a>, <a href="#">15</a> and <a href="#">16</a>: added</li> <li>• <a href="#">Figure 5</a> to <a href="#">8</a> and <a href="#">Figure 11</a> to <a href="#">14</a>: updated</li> <li>• <a href="#">Section 8 “Test information”</a>: added</li> <li>• <a href="#">Section 10 “Soldering”</a>: added</li> <li>• <a href="#">Section 12 “Legal information”</a>: updated</li> </ul>		
PEMD3_PIMD3_PUMD3 v.10	20091115	Product data sheet	-	PEMD3_PIMD3_PUMD3 v.9
PEMD3_PIMD3_PUMD3 v.9	20050518	Product data sheet	-	PEMD3_PIMD3_PUMD3 v.8
PEMD3_PIMD3_PUMD3 v.8	20041206	Product data sheet	-	PEMD3_PUMD3 v.7

## 12. Legal information

### 12.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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## 12.4 Trademarks

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## 13. Contact information

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## 14. Contents

<b>1</b>	<b>Product profile</b> . . . . .	<b>1</b>
1.1	General description . . . . .	1
1.2	Features and benefits . . . . .	1
1.3	Applications . . . . .	1
1.4	Quick reference data . . . . .	1
<b>2</b>	<b>Pinning information</b> . . . . .	<b>2</b>
<b>3</b>	<b>Ordering information</b> . . . . .	<b>2</b>
<b>4</b>	<b>Marking</b> . . . . .	<b>2</b>
<b>5</b>	<b>Limiting values</b> . . . . .	<b>3</b>
<b>6</b>	<b>Thermal characteristics</b> . . . . .	<b>4</b>
<b>7</b>	<b>Characteristics</b> . . . . .	<b>7</b>
<b>8</b>	<b>Test information</b> . . . . .	<b>11</b>
8.1	Quality information . . . . .	11
<b>9</b>	<b>Package outline</b> . . . . .	<b>11</b>
<b>10</b>	<b>Soldering</b> . . . . .	<b>12</b>
<b>11</b>	<b>Revision history</b> . . . . .	<b>15</b>
<b>12</b>	<b>Legal information</b> . . . . .	<b>16</b>
12.1	Data sheet status . . . . .	16
12.2	Definitions . . . . .	16
12.3	Disclaimers . . . . .	16
12.4	Trademarks . . . . .	17
<b>13</b>	<b>Contact information</b> . . . . .	<b>17</b>
<b>14</b>	<b>Contents</b> . . . . .	<b>18</b>

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